## Portable Cost-Effective 3D Digital AESA Radar –Technology Development and Its Impact on EW

### Speaker:

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# **Tron Future Tech Inc.**



### About Us:

>30% employee with Ph.D. degrees from Caltech/USC/MIT/UCLA/NTU/NCTU/NTHU etc.

#### Address:

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### **Our Mission:**

• We help our customers collect, analyze and utilize valuable data through fundamental sensor and communication inventions.

### Area of Focus:

- Ultrathin all-digital/hybrid phased array based radar/communication turnkey systems.
- Value-added data processing infrastructure.

### Our Taiwanese customers in 2019:

- National Space Program Office.
- R.O.C. Military.
- Changhua offshore wind farms. (via. Hong-Yi Ecological Co., Ltd.)

### **Our Experiences**



# Agenda

- Summary from Our EW Europe 2018/EW Asia 2019 Talks
- AESA Cost Reduction and Trade-offs
- Cost-Effective AESA and Initial Experimental Results
- Implications and Conclusions

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## Wireless Scanning Technology Development



Ref: EW Asia 2019:"Ultrathin All-Digital Software-defined Active Phased Array Technology"

## **Ultrathin Form Factor**

- AESA size can only be shrank by thickness.
- What is drives for ultrathin form factor?
  - 1. Light weight, small volume  $\rightarrow$  portable.
  - 2. Lower BOM/material usage  $\rightarrow$  cost in long run.



- What breakthroughs have been made in technology?
  - 1. Arithmetic and Logic Circuit  $\rightarrow$  80x size & performance improvement in last 12 years.
  - **2.** Analog-to-Digital Converter  $\rightarrow$  5x size & power improvement in 10 years.
  - 3. RF Power Amplifier  $\rightarrow$  GaN PA generates 10x more power with >50% efficiency.
  - 4. Transceiver Modules  $\rightarrow$  discrete to integrated TR module, >100 times size reduction.
  - 5. Packaging and Assembling → 3D-IC-stacking ball grid array (BGA) with flipchip process.

Ref: Our EW Europe 2018 Talk:" Flexibility and Thinness – How Semiconductor Technologies Shape Future Radar and Electronic Warfare?"

# Scalable Subarray (4x4)



Expect ~20mm thickness in 2020.

# The LTCC Multichip TR Modules and AiP



- The RF SoC can work with several GaAs and GaN frontends (LNA/PA).
- Production test approaches are proposed and reported in PIERS 2018.

### **4x8 Array Pattern Measurement**



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## **4x8 Sequential Scanning Pattern**



- Measured peak EIRP ~ 48 dBm with 32 CMOS only TXs.
- Expected: 66dBm with 32 CMOS TXs + 32 GaN PAs.

Technical Details published in IEEE Radar Conference 2019. Tron Future Tech

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### AESA Radar Cost Source: (1) Phased Array



#### Phased array is a highly repetitive structure. The performance is proportional to the array size.

### The cost of phased array is proportional to the total no. of array elements and PA power.

[Ref] Herd J.S., Conway M.D. The Evolution to Modern Phased Array Architectures. *Proceedings of the IEEE*, 2016, Vol. 104, No. 3, pp. 519-529.

### **AESA Radar Cost Source: (2) Thermal Cooling**



- Air-cooling has a heat density limit ~ 10kW/m<sup>2</sup>
- Liquid-cooling removes 20~50 times more heat with 4~10 times the cost.

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[Ref] Herd J.S., Conway M.D. The Evolution to Modern Phased Array Architectures. *Proceedings of the IEEE*, 2016, Vol. 104, No. 3, pp. 519-529.

### **AESA Radar Cost Source:**

### (3) Digital Processor



- Today's AESAs use Commercial Off-The-Shelf (COTS) devices such as FPGA, GPU, CPUs.
- Digital AESA will increase computing power requirements, but we get lots of additional benefits in return. We expect the processor cost to increase in the future.
- NRE cost for 130nm process is ~\$200K, while 16nm > \$3M.

### **AESA Radar Cost Structure Example**





- Only hardware production cost is considered.
- Software, field test expenses and other NRE are not listed.
- To dramatically reduce AESA cost, we need to dramatically reduce no. of elements.

[Ref] Herd J.S., Conway M.D. The Evolution to Modern Phased Array Architectures. *Proceedings of the IEEE*, 2016, Vol. 104, No. 3, pp. 519-529.

## **Cost Reduction and Sidelobes Issues**

### • N=512 → N=64

- Peak Power Reduced.
- Mainlobe beamwidth Increased .
- Sidelobe Increased .
- Why sidelobes matter?
  - False targets.
- Though we can still distinguish range and velocity (MTI) bins.



# **Digital Beamforming v.s. Analog Beamforming**



- Typical analog elementary errors:
  - $\pm 1$ dB amplitude variation,  $\pm 3^{\circ}$  phase error.
- All digital array achieve similar level of sidelobe rejection using 2~10 times less elements than analog counterparts.
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### **3D AESA Cost Reduction**

- Fully Populated Planar AESA.
- Orthogonal Linear Digital AESA.



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No. of Elements	W*H	H (TX), W (RX)	1024 → 32 (3% cost)	
Peak Power	$P_0 * W * H$	$\sim P_0 * (H)$	3% original power	
Antenna Gain	$\propto W * H$	$\propto W$ (RX), $\propto H$ (TX)	3% gain for RX & TX	
Max. Dwell Time	T <sub>0</sub>	Т <sub>0</sub> * Н	32 times with RX multibeam	
SNR	SNR <sub>0</sub>	$SNR_0 \cdot H/H^3$	1/1024 → (18% detection range)	
Cost per Area	C <sub>0</sub>	C <sub>0</sub>	Similar cost per coverage area.	ıre Tech

# **Basic Operational Concepts**

- Transmitter fan-shaped pattern.
- Receiver multi-beam pattern.

• Equivalent transmit-to-receive patterns.



• Equivalent Radar Beam Pattern



• TX Vertical Scanning.

- RX Horizontal Multibeam Scanning.
- This is not the only operations, but a working example to show how it can work.

## **The Cost-Effective AESA Prototype**

TX



Specifications				
Number of Elements	$1 \times 16$ TX (CMOS array with GaN PAs*) $1 \times 16$ RX (CMOS array with GaN LNAs*)			
Architecture	Two hierarchy AESA			
Frequency	8-9.5 GHz			
Phase-shifting	All-digital			
Applications	Radar/Communication/EW			
Size (W/ Structure)	63 cm x 63 cm x 13 cm			
Antenna Size (W/O Separator)	1×16 TX**: 31.7 cm x 7.03 cm 1×16 RX**: 31.7 cm x 7.75 cm			
Weight (W/O Structure)	2.545 kg			
Angular Scanning Range	±60° (RX) / ±45°(TX)			
Peak EIRP	63 dBm			
Only two external interface	<ol> <li>AC Power: 90-230 VAC (Optional 20- 60V VDC) 700W peak.</li> <li>Ethernet.</li> </ol>			

GaN PA: Qorvo TGA 2598; GaN LNA: Qorvo TGA 2512 \* \*\* 1×16 frontend has two dummy antenna beside the main 16 This slide contain proprietary information which is currently U.S. patent pending.

## **1TX 16RX LFM Multibeam Radar Experiments**

• Distance: A=924m , B=808.5m, C=721.5m, D=831m, E=1101m, F=382.5m , G=530m





- This experiment used 1 TX and the 16-element RX array is located at 7F (around 35m from the ground).
- An absorber is used in front of the RX to limit the elevation angles so that close-in reflections from the ground are not received.
- The transmit pulse is 32 uSec LFM, and received signal is averaged by 64 PRIs, and then passes through the matched filter of the LFM signal.

## **1TX 16RX LFM Multibeam Radar Experiments**



- From the top view, it is found that the light spots in the result plots of the experiment are perfected matched to the buildings shown on a map of the local are (map data from Google map).
- The farthest range of this experiment is (768pt-32pt)\*1.5 = 1104m.

## **16TX 16RX 3D Surveillance Experiments**



## **3D Drone Tracking Example**



• Drone: DJI Phantom 4 (~0.01m<sup>2</sup> RCS)<sub>o</sub>

## Most Likely S/X-band AESA Production Spec.

#### S-band (2.9-3.1GHz)



No. of Elements	32 TX, 32-48 RX (TBD)
Peak EIRP	25kW
Weight	<20kG
Est. Power Consumption	~200W
Beamwidth	3.5°(H), 7°(V)
Simulated Range	>20km@2m <sup>2</sup> , 2Hz Tracking
First Shipping for Field Test	Sept. 30, 2019



No. of Elements	64 TX, 64-96 RX (TBD)
Pea EIRP	20kW
Weight	<15kG
Est. Power Consumption	~150W (TBD)
Beamwidth	2°(H), 3.5°(V)
Simulated Range	>10km@2m <sup>2</sup> , 2Hz Tracking
First Shipping for Field Test	TBD
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### **AESA in Future EW**



- Cost-effective AESAs begin to be pervasive to complement existing high-performance AESAs.
- Chip-scale atomic clocks enable massive software-defined AESA platform.
- Software is key to fully utilize the massive number of AESA.

### **Software Architecture**



- Global temporal-spatial database in the cloud keeps track of area being serviced and tracking data from each AESA.
- Each AESA checks out a region from the cloud, and run autonomously. Keep updating operating status to the cloud. The cloud arbiter/resolves any conflicts from each AESA.
- Cooperation between a large number of mobile AESA and conventional units while making the whole system resilient and robust with redundant units will be an important problem that needs to be extensively studied.
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# Conclusion

- AESA hardware cost is roughly proportional to array elements.
- Reducing array elements will reduce peak power (range), increase mainlobe beamwidth (number of identified targets), and reduce sidelobe rejection. Sidelobe rejection is important for preventing false targets.
- Digital AESA has a much better sidelobe rejection than an analog counterpart.
- Use of orthogonal linear AESAs can create a virtual 2D AESA, but a much smaller number of array elements.
- Reducing array elements, and highly integrated T/R module, we can make mid/short-range AESA light-weight and cost-effective <u>today</u>.
- EW community enters a new era of massive number of AESAs.

# Q & A

- Critiques, questions, and suggestions are highly welcome.
- Thank you for your attentions.
- Email: yw@tronfuturetech.com

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